

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A film-type catalyst for production of a tertiary amine, which is used in producing a tertiary amine from an alcohol and a primary or secondary amine as the starting material;

wherein said film-type catalyst has a thickness of 500 μm or less and a pore volume of not less than 0.5 mL/m².

2. (Original) The film-type catalyst according to claim 1, which has a thickness of 100 μm or less.

3. (Original) The film-type catalyst according to claim 1 or 2, which comprises copper.

4. (Currently Amended) The film-type catalyst according to claim 1 [[or 2]], which is fixed on the surface of a substrate.

5. (Currently amended) The film-type catalyst according to claim 1, which has a pore volume of 0.5 to 30 mL/m² and comprises synthetic resin in an amount of 20 to 80 parts by weight relative to 100 parts by weight of a powdery catalyst active substance on the basis of the starting material.

6. (Original) The film-type catalyst according to claim 5, wherein the synthetic resin comprises thermosetting resin.

7. (Original) The film-type catalyst according to claim 5 or 6, wherein the synthetic resin comprises phenol resin.

8. (Currently Amended) The film-type catalyst according to claim 4 ~~1 or 2~~, wherein the substrate is a metal foil.

9. (Currently Amended) The film-type catalyst according to claim 4 ~~1 or 2~~, wherein the substrate is a honeycomb structure.

10. (Currently Amended) A process for producing a tertiary amine, which comprises a step of reacting an alcohol with a primary or secondary amine in the presence of ~~[[the]]~~ a film-type catalyst ~~of claim 1 or 2~~ having a thickness of 500 μ m or less and a pore volume of not less than 0.5 mL/m².

11. (Cancelled)

12. (New) The process according to claim 10, wherein the film-type catalyst has a thickness of 100 μ m or less.

13. (New) The process according to claim 10, wherein the film-type catalyst comprises copper.

14. (New) The process according to claim 10, wherein the film-type catalyst is fixed on the surface of a substrate.

15. (New) The process according to claim 14, wherein the substrate is a metal foil.

16. (New) The process according to claim 14, wherein the substrate is a honeycomb structure.